ASML Announces Plan to Optimize Capital Structure: Eurobond Issue Followed by Capital Repayment and Reverse Stock Split

VELDHOVEN, the Netherlands, May 31, 2007 – ASML Holding NV (ASML) today announced that it will further optimize its capital structure through an inaugural Eurobond benchmark issue. The proceeds will be used to fund part of approximately EUR 960 million that will be returned to the shareholders in combination with a reverse stock split.

The intended offering in the Eurobond market of a benchmark-size Euro denominated issue is expected to take place in the coming weeks subject to market conditions. The notes will only be offered to institutional investors outside the United States in reliance on Regulation S under the US Securities Act of 1933, and are expected to be listed on the Euro MTF market of the Luxembourg Stock Exchange.

About ASML

ASML is the world’s leading provider of lithography systems for the semiconductor industry, manufacturing complex machines that are critical to the production of integrated circuits or chips. Headquartered in Veldhoven, the Netherlands, ASML is traded on Euronext Amsterdam and NASDAQ under the symbol ASML.

This press release is not an offer for sale of, or a solicitation to purchase or subscribe for, any securities in the United States. The bonds discussed in this press release have not been, and will not be registered under the U.S. Securities Act 1933, and may not be offered or sold in the United States absent registration or an exemption from registration thereunder.

Lucas van Grinsven
Head of Communications
+31 40 268 3949
corpcom@asml.com

Craig DeYoung
VP Investor Relations Asia
+852 2295 1168

Marcel Kemp
Director Investor Relations - Europe
+31 40 268 6494